

Amendments to the CLAIMS

1-48. (Cancelled)

49. (Currently Amended) A light emitting device package, comprising:

a base having an entire top surface that is flat;

a light emitting device ~~directly~~ on the flat top surface of the base;

an electrical circuit layer including a circuit with a predetermined pattern to electrically connect to the light emitting device, and including at least one end portion, a part of the at least one end portion being placed adjacent to the light emitting device;

an electrode layer disposed above ~~a tip portion of the at least one end~~ a portion of the electrical circuit layer, and configured to electrically connect between the light emitting device and the electrical circuit layer;

a screen layer having an opening and disposed on the base adjacent to the light emitting device, the screen layer guiding a resin material to define a shape of a lens; and

a the lens formed with the resin material guided by the screen layer, and covering the light emitting device and the electrode layer,

wherein the electrical circuit layer is disposed on the base so as not to protrude beyond edges of the base.

50. (Previously Presented) The light emitting device package of claim 49, wherein an entire bottom surface of the electrode layer is in contact with the electrical circuit layer.

51. (Previously Presented) The light emitting device package of claim 49, wherein the electrode layer is separated from the light emitting device and does not directly contact the light emitting device.

52. (Previously Presented) The light emitting device package of claim 49, wherein the lens is a molding which completely fills up any space between the light emitting device and the electrode layer.

53. (Previously Presented) The light emitting device package of claim 49, wherein the entire electrode layer is encapsulated by the lens.

54. (Previously Presented) The light emitting device package of claim 49, further comprising an insulating layer between the electrical circuit layer and the base.

55. (Previously Presented) The light emitting device package of claim 49, wherein a top surface of the electrode layer is plated.

56. (Previously Presented) The light emitting device package of claim 49, wherein the base is made of a metal.

57. (Previously Presented) The light emitting device package of claim 49, further comprising a heat sink disposed on a bottom surface of the base.

58. (Previously Presented) The light emitting device package of claim 49, wherein the base has a hole.

59. (Previously Presented) The light emitting device package of claim 58, wherein the hole is in contact with a heat sink disposed on a bottom surface of the base.

60. (Previously Presented) The light emitting device package of claim 49, further comprising a plating layer on the electrode layer.

61. (Currently Amended) A light emitting device comprising:

at least one light emitting package, each including:

a base having an entire top surface that is flat,

a light emitting unit ~~directly~~ on the flat top surface of the base,

an electrical circuit layer including a circuit with a predetermined pattern to electrically connect to the light emitting device, and including at least one end portion, a part of the at least one end portion being placed adjacent to the light emitting unit,

an electrode layer disposed above ~~a tip portion of the at least one end portion~~ a portion of the electrical circuit layer, and configured to electrically connect between the light emitting unit and the electrical circuit layer,

a screen layer having an opening and disposed on the base adjacent to the light emitting unit, the screen layer guiding a resin material to define a shape of a lens, and

~~a the lens~~ formed with the resin material guided by the screen layer, and covering the light emitting unit and the electrode layer,

wherein the electrical circuit layer is disposed on the base so as not to protrude beyond edges of the base.

62. (Previously Presented) The light emitting device of claim 61, wherein the light emitting device includes more than one said light emitting package.

63. (Previously Presented) The light emitting device of claim 61, wherein an entire bottom surface of the electrode layer is in contact with the electrical circuit layer.

64. (Previously Presented) The light emitting device of claim 61, wherein the electrode layer is separated from the light emitting unit and does not directly contact the light emitting unit.

65. (Previously Presented) The light emitting device of claim 61, wherein the lens is a molding which completely fills up any space between the light emitting unit and the electrode layer.

66. (Previously Presented) The light emitting device of claim 61, wherein the entire electrode layer is encapsulated by the lens.

67. (Previously Presented) The light emitting device of claim 61, wherein each of the at least one light emitting package further comprises a heat sink disposed on a bottom surface of the base.

68. (Previously Presented) The light emitting device of claim 61, wherein the base has a hole.

69. (Previously Presented) The light emitting device of claim 68, wherein the hole is in contact with a heat sink disposed on a bottom surface of the base.

70. (Previously Presented) The light emitting device of claim 61, wherein each of the at least one light emitting package further comprises a plating layer on the electrode layer.